









## **FABRICATION NOTES:**

Fabricate per IPC-6011 & IPC-6012 CLASS 2 Inspect per IPC-A-600 CLASS 2 Test per IPC-TM-650

- \* PCB has 4 copper layers
- \* Copper thicknesses are finished and include base foil plus Cu plating on plated layers.
- \* PCB thickness: 63mil +/- 3mil
- \* Min. trace width/clearance: 4/4mil
- \* Min. hole drill/ring: 8mil/16mil
- \* All vias-in-pad shall be plugged and plated over (VIPPO)
- \* Soldermask gang relief is allowed for pads in same footprint, if footprint is NSMD.
- \* Silkscreen, non-conductive epoxy ink, color: white
- \* Remove slikscreen as needed to prevent ink on any exposed copper

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- \* Surface finish: ENIG
- \* Hole dimensions are finished size, +/-3mil
- \* Linear board dimension tolerance: +/-10mil
- \* Bow, twist, warp not to exceed 0.75% of greatest diagonal span
- \* PCB shall be UL Recognized printed wiring board (ZPMV2), minimum flammability rating 94V-0
- \* PCB shall be marked with fabricator company or trade name, UL mark, and date code using legend ink on secondary side
- \* All PCBs shall be electrically tested for opens and shorts per gerber. Test marking shall be marked on secondard side.

Fabricator shall panelize the PCB using mouse bites and tab routing. V-scoring not allowed.

Controlled impedance differential pairs shall be within +/-10% of target impedance. See sheets below for more detail.

Title: BW2098POE

Number: D2098000 Revision: R2M1 E2

Date: 7/23/2020 Sheet: 1 of 5

Drawn by: Brian Weinstein PROPRIETARY AND CONFIDENTIAL

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Layer 3 (Scale 1:1)

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B C D







